Quad Flat No-Lead Plastic Package (QFN) Micro Lead Frame Plastic Package (MLFP)





e

L56.8x8A

56 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (COMPLIANT TO JEDEC MO-220VLLD-2 ISSUE C)

	MILLIMETERS			
SYMBOL	MIN	NOMINAL	MAX	NOTES
А	0.80	0.90	1.00	-
A1	-	-	0.05	-
A2	-	-	1.00	9
A3	0.20 REF			9
b	0.18	0.23	0.30	5, 8
D	8.00 BSC			-
D1	7.75 BSC			9
D2	5.95	6.10	6.25	7, 8
E	8.00 BSC			-
E1		7.75 BSC		9
E2	5.95	6.10	6.25	7, 8
е	0.50 BSC			-
k	0.25	-	-	-
L	0.30	0.40	0.50	8
L1	-	-	0.15	10
Ν	56			2
Nd	14			3
Ne		14		3
Р	-	-	0.60	9
θ	-	-	12	9

NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd and Ne refer to the number of terminals on each D and E.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
- 8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
- 9. Features and dimensions A2, A3, D1, E1, P & θ are present when Anvil singulation method is used and not present for saw singulation.
- 10. Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

